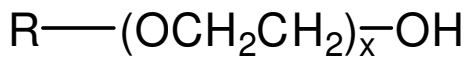
WHAT IS CLAIMED IS:

1. A polishing slurry composition, comprising a non-ionic surfactant represented by formula (1),



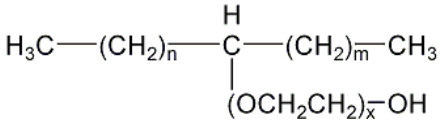
formula (1)

wherein x is an integer between 1 and 50, and wherein the non-ionic surfactant is a secondary alcohol ethoxylate, and a pH value of the polishing slurry composition is between 7 and 11.

2. The polishing slurry composition of claim 1, wherein x is an integer between 7 and 40.

3. The polishing slurry composition of claim 1, wherein R is selected from a group consisting of a C3-C50 alkyl group, a C3-C50 hydroxyalkyl group, a C6-C55 benzylalkyl group and a C6-C55 phenylalkyl group.

4. The polishing slurry composition of claim 1, wherein the non-ionic surfactant is represented by formula (2),



formula (2)

wherein m+n is an integer between 2 and 15.

5. The polishing slurry composition of claim 1, wherein based on a total weight of the polishing slurry composition, a content of the non-ionic surfactant is between 5 ppm and 5000 ppm.

6. The polishing slurry composition of claim 5, wherein based on the total weight of the polishing slurry composition, the content of the non-ionic surfactant is between 10 ppm and 1000 ppm.

7. The polishing slurry composition of claim 1, further comprising an oxidizing agent.

8. The polishing slurry composition of claim 7, wherein the oxidizing agent is one or